12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20260217004.1
Design change for select devices
Change Notification / Sample Request

Date: February 19, 2026
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Change Management Team
SC Business Services

20260217004.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TLC555CP	NULL
TLC555CDR	NULL
TLC555QDRG4	TLC555QDRG4
TLC555IP	NULL
TLC555IDR	NULL
TLC555QDR	TLC555QDR

Technical details of this Product Change follow on the next page(s).

PCN Number:	20260217004.1	PCN Date:	February 19, 2026
Title:	Design change for select devices		
Customer Contact:	Change Management Team	Dept:	Quality Services
Proposed 1st Ship Date:	May 20, 2026	Sample requests accepted until:	April 20, 2026*

***Sample requests received after April 20, 2026 will not be supported.**

Change Type:

☐	Assembly Site	☒	Design	☐	Wafer Bump Material
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Process
☐	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Material
☒	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

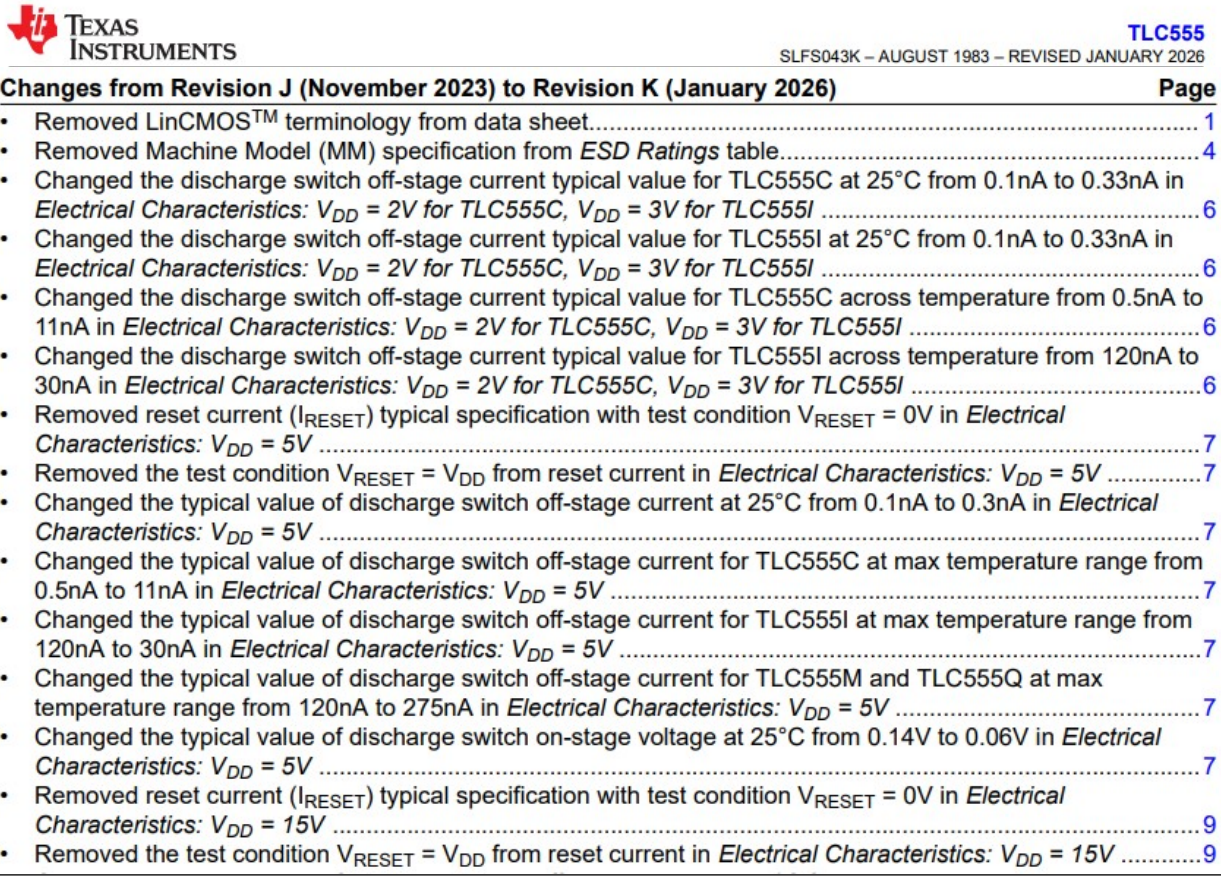
PCN Details

Description of Change:

Texas Instruments is pleased to announce a die design update from the last revision to better match the historical behavior of the affected devices.

The die revision was also changed as a result of the process change.

The datasheet will be changing as a result of the design change.



TEXAS INSTRUMENTS

TLC555

SLFS043K – AUGUST 1983 – REVISED JANUARY 2026

Changes from Revision J (November 2023) to Revision K (January 2026) **Page**

- Removed LinCMOS™ terminology from data sheet 1
- Removed Machine Model (MM) specification from *ESD Ratings* table 4
- Changed the discharge switch off-stage current typical value for TLC555C at 25°C from 0.1nA to 0.33nA in *Electrical Characteristics:* V_{DD} *= 2V for TLC555C,* V_{DD} *= 3V for TLC555I* 6
- Changed the discharge switch off-stage current typical value for TLC555I at 25°C from 0.1nA to 0.33nA in *Electrical Characteristics:* V_{DD} *= 2V for TLC555C,* V_{DD} *= 3V for TLC555I* 6
- Changed the discharge switch off-stage current typical value for TLC555C across temperature from 0.5nA to 11nA in *Electrical Characteristics:* V_{DD} *= 2V for TLC555C,* V_{DD} *= 3V for TLC555I* 6
- Changed the discharge switch off-stage current typical value for TLC555I across temperature from 120nA to 30nA in *Electrical Characteristics:* V_{DD} *= 2V for TLC555C,* V_{DD} *= 3V for TLC555I* 6
- Removed reset current (I_{RESET}) typical specification with test condition V_{RESET} = 0V in *Electrical Characteristics:* V_{DD} *= 5V* 7
- Removed the test condition V_{RESET} = V_{DD} from reset current in *Electrical Characteristics:* V_{DD} *= 5V* 7
- Changed the typical value of discharge switch off-stage current at 25°C from 0.1nA to 0.3nA in *Electrical Characteristics:* V_{DD} *= 5V* 7
- Changed the typical value of discharge switch off-stage current for TLC555C at max temperature range from 0.5nA to 11nA in *Electrical Characteristics:* V_{DD} *= 5V* 7
- Changed the typical value of discharge switch off-stage current for TLC555I at max temperature range from 120nA to 30nA in *Electrical Characteristics:* V_{DD} *= 5V* 7
- Changed the typical value of discharge switch off-stage current for TLC555M and TLC555Q at max temperature range from 120nA to 275nA in *Electrical Characteristics:* V_{DD} *= 5V* 7
- Changed the typical value of discharge switch on-stage voltage at 25°C from 0.14V to 0.06V in *Electrical Characteristics:* V_{DD} *= 5V* 7
- Removed reset current (I_{RESET}) typical specification with test condition V_{RESET} = 0V in *Electrical Characteristics:* V_{DD} *= 15V* 9
- Removed the test condition V_{RESET} = V_{DD} from reset current in *Electrical Characteristics:* V_{DD} *= 15V* 9

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
TLC555	SLFS043J	**SLFS043K**	http://www.ti.com/product/TLC555

Qual details are provided in the Qual Data Section.

Reason for Change:

Change behavior to match that of legacy devices.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

Review the SDP and datasheet for full evaluation of the change based on the customer use case.

Changes to product identification resulting from this PCN:

Die Rev:

Current Die Rev [2P]	New Die Rev [2P]
F	**B**

Sample product shipping label (not actual product label):

Product Affected:

TLC555CDR	TLC555IDR	TLC555QDR	TLC555QDRG4
TLC555QDRNS	TLC555CP	TLC555IP	

For alternate parts with similar or improved performance, please visit the product page on TI.com

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Attributes	Qual Device: TLC555QDR	QBS Process Reference: OPA391DCKT	QBS Package Reference: LM358DR	QBS Package Reference: TLC555QDRQ1	QBS Package Reference: TLC3555QDRQ1
Die Attributes					
Wafer Fab Supplier	RFAB	RFAB	SH-BIP-1	RFAB	RFAB
Wafer Process	HPA9	HPA9	JI1	HPA9	HPA9
Die Size (L,W) (um)	744 x 672	676 x 760	1348.0034 x 1088.009	734 x 652	762 x 680
Passivation	Silicon Oxynitride	Silicon Oxynitride	Silicon Oxynitride	Silicon Oxynitride	Silicon Oxynitride
Package Attributes					
Assembly Site	FMX	HFTFAT	FMX	FMX	FMX
Package Group	SOIC	SOT-SC70	SOIC	SOIC	SOIC
Package Designator	D	DCK	D	D	D
Package Size (mm)	4.9 x 3.9	2 x 1.25	4.9 x 3.9	4.9 x 3.9	4.9 x 3.9
Body Thickness (mm)	1.58	0.9	1.58	1.58	1.58
Pin Count	8	5	8	8	8
Lead Finish	NIPDAU	NIPDAU	NIPDAU	NIPDAU	NIPDAU

Attributes	Qual Device: TLC555QDR	QBS Process Reference: OPA391DCKT	QBS Package Reference: LM358DR	QBS Package Reference: TLC555QDRQ1	QBS Package Reference: TLC3555QDRQ1
Lead Pitch(mm)	1.27	0.65	1.27	1.27	1.27
Mount Compound Supplier	HENKEL	SUMITOMO	HENKEL	HENKEL	HENKEL
Mount Compound Supplier Number	QMI 505MT	CRM-1076NS	QMI 505MT	QMI 505MT	QMI 505MT
Mold Compound Supplier	SUMITOMO	SUMITOMO	SUMITOMO	SUMITOMO	SUMITOMO
Mold Compound Supplier Number	EME-G633C	EME-G700LTD	EME-G633C	EME-G633C	EME-G633C
Bond Wire Composition	CU	CU	CU	CU	CU
Bond Wire Diameter(um)	20.32	20.32	24.3	20.3	20.32
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device TLC555QDR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2508-035

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TLC555IDR	QBS Process Reference: OPA391DCKT	QBS Product Reference: TLC555IDR	QBS Package Reference: TCAN1044VDRQ1	QBS Package Reference: OPA2991QDRQ1	QBS Product Reference: TLC555QDR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	3/231/0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	3/231/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	3/135/0	-
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	-	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	3/66/0	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	3/30/0	3/30/0	-
ESD	E2	ESD CDM	-	1000 Volts	-	-	-	-	-	1/3/0

Type	#	Test Name	Condition	Duration	Qual Device: TLC555IDR	QBS Process Reference: OPA391DCKT	QBS Product Reference: TLC555IDR	QBS Package Reference: TCAN1044VDRQ1	QBS Package Reference: OPA2991QDRQ1	QBS Product Reference: TLC555QDR
ESD	E2	ESD CDM	-	250 Volts	-	-	1/3/0	-	-	-
ESD	E2	ESD HBM	-	1000 Volts	-	-	1/3/0	-	-	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	-	1/3/0	-	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/Pass	-	1/Pass	-	-	1/Pass

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device TLC555IDR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2508-036

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TLC555IP	QBS Package Reference: NE5532P	QBS Package Reference: TS12A4514P	QBS Process Reference: OPA391DCKT	QBS Package Reference: SN74HC00N	QBS Package Reference: ULN2003AN	QBS Package Reference: NE556N	QBS Product Reference: TLC555QDR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	-	-	3/231/0	-	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	1/77/0	-	-	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	-	1/77/0	1/77/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	1/77/0	-	1/77/0	1/77/0	1/77/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	-	1/77/0	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	1/77/0	-	-	-	1/77/0	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	3/231/0	-	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	3/2400/0	-	-	-	-
SD	C3	PB-Free Solderability	8 Hours Steam Age	-	-	3/66/0	-	-	-	-	-	-

Type	#	Test Name	Condition	Duration	Qual Device: TLC555IP	QBS Package Reference: NE5532P	QBS Package Reference: TS12A4514P	QBS Process Reference: OPA391DCKT	QBS Package Reference: SN74HC00N	QBS Package Reference: ULN2003AN	QBS Package Reference: NE556N	QBS Product Reference: TLC555QDR
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	3/66/0	-	-	-	-	-	-
ESD	E2	ESD CDM	-	1000 Volts	1/3/0	-	-	-	-	-	-	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	-	-	-	-	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	-	-	-	-	-	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/Pass	-	-	-	-	-	-	1/Pass

- QBS: Qual By Similarity, also known as Generic Data
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2508-037

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a ‘product qualification family’ for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled “QBS Process” (for wafer fab process), “QBS Package” (for assembly process) and “QBS Product” (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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